

6X

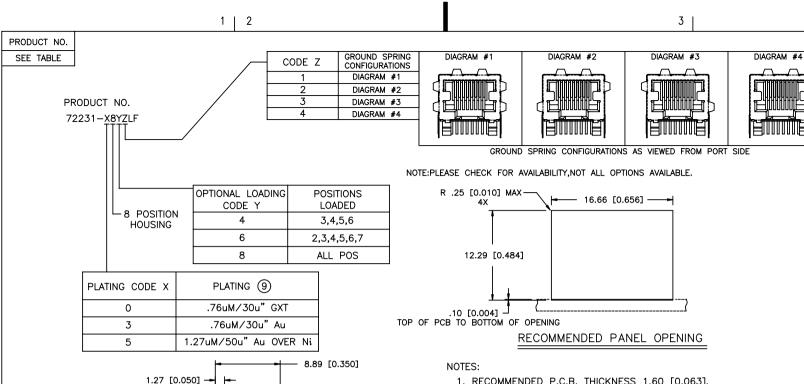
8.890 [0.3500]

6.350 [0.2500]

ø1.57 [0.062] 2X

EDGE OF PCB





- 1.270 [0.0500]

Ø0.89 [0.035] 8X

ø3.25 [0.128] 2X

4.70 [0.185]

11.43 [0.450]

2.03 [0.080]

3.05 [0.120] 2X

ф<sup>6</sup> ф<sup>5</sup>

- 15.49 [0.610] --

RECOMMENDED P.C.B. LAYOUT AS VIEWED FROM TOP SIDE (COMPONENT SIDE)

2

- 1. RECOMMENDED P.C.B. THICKNESS 1.60 [0.063].
- 2. HOUSING MATL: HIGH TEMPERATURE THERMOPLASTIC MATERIAL. UL94V-0, COLOR BLACK.
- 3. CONTACTS MATL: PHOS BRONZE ALLOY ROUND WIRE. SEE TABLE FOR PLATING.
- 4. SHIELD MATL: PHOS BRONZE ALLOY, BRIGHT TIN PLATE OVER NICKEL UNDERPLATING PER BUS-15-002/M.
- 5. TWO LAYERS OF HIGH TEMP. INSULATING TAPE BETWEEN SHIELD AND SIGNAL CONTACTS.
- (6.) LF SUFFIX AT THE END OF PART NUMBER IS LEAD FREE.
- 7. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 15 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.5mm MINIMUM THICK CIRCUIT BOARD. SEE APPLICATION NOTES/PROCEDURES IF THEY ARE AVAILABLE.
- (8.) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008.
- (9.) PLATING OPTIONS: MAY BE EITHER GOLD OR GXT PLATED AT MANUFACTURER'S OPTION.

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PDM: Rev:M

cage code STATUS: Release 526 Printed: Feb 19, 2008